



Material Content Data Sheet



Sales Product Name				BSC100N10NSF G		Issued		1. August 2018	
MA#				MA001601262					
Package				PG-TDSON-8-1		Weight*		122.80 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.418	4.41	4.41	44118	44118	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		92		
	non noble metal	iron	7439-89-6	0.038	0.03		308		
	non noble metal	copper	7440-50-8	37.762	30.76	30.80	307510	307910	
	non noble metal	copper	7440-50-8	0.028	0.02	0.02	229	229	
wire	non noble metal	copper	7440-50-8	0.028	0.02	0.02	229	229	
encapsulation	organic material	carbon black	1333-86-4	0.078	0.06		634		
	plastics	epoxy resin	-	5.528	4.50		45016		
	inorganic material	silicondioxide	60676-86-0	33.323	27.14	31.70	271367	317017	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.18	1.18	11821	11821	
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1348	1348	
solder	non noble metal	tin	7440-31-5	0.081	0.07		660		
	noble metal	silver	7440-22-4	0.101	0.08		825		
	non noble metal	lead	7439-92-1	3.868	3.15	3.30	31499	32984	
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	iron	7439-89-6	0.011	0.01		92		
	non noble metal	copper	7440-50-8	11.320	9.22	9.23	92184	92304	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	non noble metal	iron	7439-89-6	0.022	0.02		182		
	noble metal	silver	7440-22-4	1.289	1.05		10501		
	non noble metal	copper	7440-50-8	22.292	18.15	19.23	181531	192269	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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